## LNJ810C67RA

### Hight Bright Surface Mounting Chip LED

SV (Side View) -Case Type

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	50	mW	
Forward current	$I_{\mathrm{F}}$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	Topr	-25 to +80	°C	
Storage temperature	T <sub>stg</sub>	-30 to +85	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

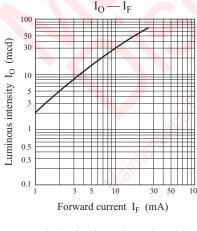
#### ■ Lighting Color

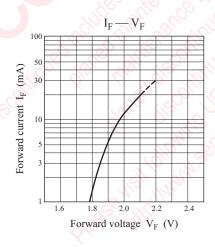
• Soft Orange

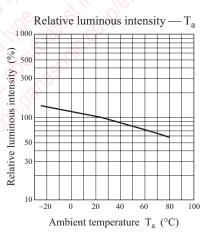
#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

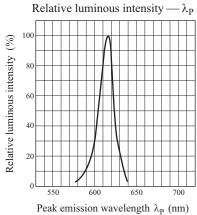
Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Luminous intensity *	$I_{O}$	$I_F = 10 \text{ mA}$	2402	24	30	55	mcd
Reverse current	$I_R$	$V_R = 4 V$				100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$	1000		1.95	2.5	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$	Will City	600	615	625	nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$	collo aco	Ó	20	60	nm

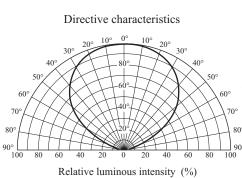
Note) \*: Measurement tolerance: ±20%

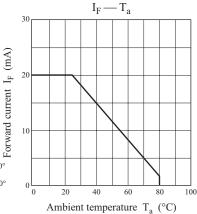








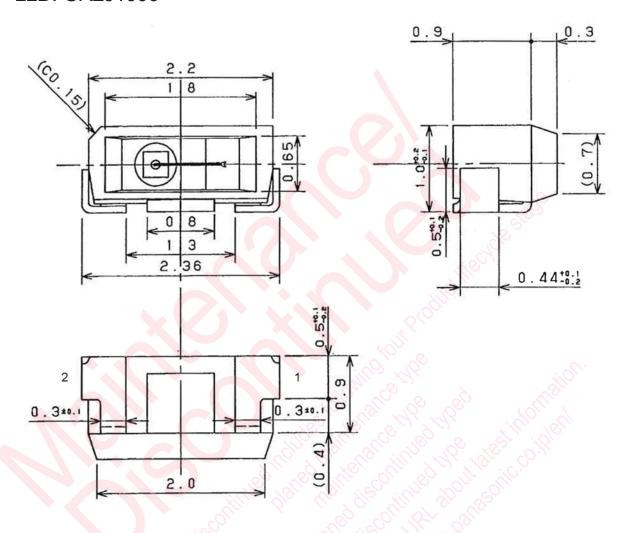




LNJ810C67RA Panasonic

■ Package (Unit: mm)

## LLDFSR2J1000



- Pin name
  - 1: Anode
  - 2: Cathode

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